IN THE SPECIFICATION

1. Please amend the title as follows.

~~A METHOD AND APPARATUS FOR LUBRICATING MICROELECTROMECHANICAL DEVICES IN PACKAGES~~ PACKAGED MICROELECTROMECHANICAL DEVICE WITH LUBRICANT

2. Please amend paragraph [0016] as follows.

[0016] The present invention provides a method and apparatus for lubricating surfaces of microelectromechanical devices package by placing a container having selected lubricant in the package in which the microelectromechanical device is disposed. The lubricant evaporates from an opening of the container and contacts the surfaces to be lubricated. When the amount of the lubricant is in the micro liter order and needs to be precisely controlled, the container can be a capillary tubing with an interior volume generally equal to the desired amount. The capillary tubing is placed on the package substrate on which the microelectromechanical device is disposed. The lubricant inside the capillary tubing evaporates from an opening of the tubing and contacts the target surfaces. The container having the lubricant can be placed on the package substrate before sealing the package.

3. Please amend paragraph [0017] as follows.

[0017] The container may also be placed within the microelectromechanical device if the container has a compatible dimension. The lubricant can be mixed with a selected diluent for improving the precise control of the amount of the lubricant and meanwhile, ~~expedite~~ expediting the transportation of the lubricant from inside the container to the target surfaces.

4. Please amend paragraph [0018] as follows.

[0018] Turning to the drawings, FIG. 1 illustrates a perspective view of an exemplary microelectromechanical device package. Microelectromechanical device package 100 comprises microelectromechanical device 108 attached to package substrate 102. The package substrate may take any desired shapes and forms; ~~shape and form~~ and may comprise any suitable materials ~~material~~. In this particular example, the package substrate is a ceramic and has a cavity in which the ~~microelectro-mechanical~~ microelectromechanical device can be disposed. Lubricant container 110 is placed on the package substrate at a location proximate to the